

20-3060 POTTING AND ENCAPSULATING EPOXY RESIN

DESCRIPTION:

20-3060 is a general purpose, low viscosity epoxy potting and encapsulating resin system. This is a 100% solids system. It therefore does not contain any solvents.

20-3060 is a filled system resulting in excellent dimensional stability and extremely low shrinkage. 20-3060 is characterized by exceptional resistance to impact, vibration, and thermal shock. In addition, this versatile resin system is machinable and ideal for use with meter mix dispensing equipment.

Due to its high purity, 20-3060 offers the ultimate in physical, thermal and electrical insulation properties. The cured polymer exhibits excellent resistance to chemicals, moisture, solvents and environmental exposure.

20-3060 is recommended for applications requiring the optimum in over-all properties and where rigid or flexible wire leads protrude directly from the encapsulant. This system eliminates microscopic cracking when leads are flexed. It also adheres extremely well to lead materials, such as vinyl, neoprene, and natural rubber.

20-3060 has found wide acceptance as an encapsulant for applications such as transformers, coils, chokes, solenoids, resistors, modules, microcircuitry, resistors, and capacitors. 20-3060 has been formulated for ease in handling and its low viscosity aids in pouring, filling voids and air pockets. In addition, the fillers in 20-3060 have been dispersed to minimize any heavy settling.

TYPICAL SPECIFICATIONS:

Viscosity, cps, 25 °C, Mixed	10,000
Color	Black
Hardness, Shore D	82
Operating Temperature Range, °C	-50 to +135
Pot Life, 200-gram Mass, 25 °C	1.30 Hours
Specific Gravity, 25 °C, Resin	1.50
Compressive Strength, psi	22,500
Linear Shrinkage, %	0.50
Tensile Strength, psi	10,000
Dielectric Strength, V/mil	460
Dielectric Constant, 100 Hz	4.51
Volume Resistivity, ohm-cm	3.99 x 10 ¹⁴
Dissipation Factor, 100 Hz	0.01

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Thermal Conductivity, W/m·K

0.43

INSTRUCTIONS FOR USE:

- A. With Catalyst 190 provides best chemical resistance in a RT cure:
 - 1. By weight, thoroughly mix 100 parts 20-3060RBK resin to 7.5 parts Catalyst 190.
 - 2. Degas, pour, and cure according to one of the following recommended cure schedules:
 - a) 25 °C 24 Hours
 - b) 60 °C 2 Hours
- B. With Catalyst 30 recommended for higher operating temperature and physical property applications:
 - 1. By weight, thoroughly mix 100 parts 20-3060RBK to 13.5 parts Catalyst 30.
 - 2. Degas, pour, and cure according to one of the following recommended cure schedules:
 - a) 85 °C 3-4 Hours
 - b) 100 °C 2-3 Hours

For optimum performance, an additional 2 hours at 185 °C is recommended.

- C. With Catalyst 150:
 - 1. By weight, thoroughly mix 100 parts 20-3060RBK to 17-20 parts Catalyst 12.
 - 2. Degas, pour, and cure according to one of the following recommended cure schedules:

a)	25 °C	24 Hours
b)	60 °C	2 Hours

STORAGE, HANDLING, & SAFETY:

Store both components at 25 °C in original containers. The expected shelf life is 12 months in original containers.

Please read the Safety Data Sheet before using this or any other chemical.

AVAILABILITY:

This product is available in quarts, gallons, and 5-gallon pails.

IMPORTANT:

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